

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

- 1-9. (Canceled)
10. (New) Microcomponent comprising a hermetically-sealed microcavity delineated by a cover comprising a first layer, in which at least one hole is formed, and a second layer making the microcavity hermetic, microcomponent comprising a third layer arranged between the first and second layer, an additional microcavity, communicating with the hole and arranged between the first and third layer, and at least one additional hole, adjacent to the additional microcavity, formed in the third layer, offset with respect to the hole and sealed by the second layer, microcomponent comprising at least one mechanically tensile-stressed layer arranged above the first layer, said mechanically tensile-stressed layer flexing in the direction of the first layer and reducing space to be sealed by the second layer.
11. (New) Microcomponent according to claim 10, wherein the additional microcavity communicates with the additional hole.
12. (New) Microcomponent according to claim 10, wherein the hole is arranged on the highest part of the microcavity.
13. (New) Microcomponent according to claim 10, wherein the offset between the hole and the additional hole is such that the additional hole does not cover the hole, even partially.
14. (New) Microcomponent according to claim 10, wherein two additional holes are associated with each hole so that a suspended bridge, formed in the third layer and delineated by the two additional holes, covers the hole.
15. (New) Method for production of a hermetically-sealed microcavity of a microcomponent according to claim 10, successively comprising

- deposition of a sacrificial layer on a substrate,
- deposition of a first layer forming a cover, on the substrate and sacrificial layer,
- etching, in the first layer, of at least one hole opening out onto the sacrificial layer,
- removal of the sacrificial layer, via the hole, so as to create a microcavity,
- deposition of a second layer, so as to make the microcavity hermetic, method comprising, after etching of the hole and before removal of the sacrificial layer,
- deposition of an additional sacrificial layer covering the hole and a part of the first layer, over the periphery of the hole,
- deposition of a third layer on the first layer and the additional sacrificial layer,
- etching of at least one additional hole, in the third layer, offset with respect to the hole and opening out onto the additional sacrificial layer, removal of the sacrificial layer and of the additional sacrificial layer being performed through the additional hole so as to create the microcavity, and deposition of the second layer being performed on the third layer so as to seal the additional hole, the method comprising deposition of at least one mechanically tensile-stressed layer, after deposition of the first layer, said mechanically tensile-stressed layer flexing in the direction of the first layer and reducing space to be sealed by the second layer.

16. (New) Method according to claim 15, wherein the third layer is mechanically tensile-stressed so that the part of the third layer released by removal of the additional sacrificial layer flexes in the direction of the first layer.

17. (New) Method according to claim 15, wherein the third layer is formed by a first mechanically tensile-stressed sub-layer covered by a second mechanically compressive-stressed sub-layer, the second sub-layer being removed after the sacrificial layers have been removed.

18. (New) Method according to claim 15, wherein, after the sacrificial layers have been removed, a mechanically tensile-stressed fourth layer is deposited on the third layer, so that the third and fourth layers flex in the direction of the first layer.